

EPIC Meeting on Advanced Microoptics: Simulation, Fabrication & Characterization at Nanoscribe

Monolithic Molding of Freeform Glass Microstructures



EV Group | At A Glance



Leading supplier of wafer processing equipment for the nanotechnology, MEMS and semiconductor markets

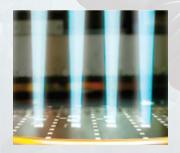
Founded in 1980 by DI Erich and Aya Maria Thallner. More than 1000 employees worldwide

Headquarters in Austria, with fully owned subsidiaries in the USA, Japan, South Korea, China and Taiwan

Recent Developments



GEMINI® FB Hybrid Bonding



EVG® MLE™ **Maskless Exposure Technology**

Nanoimprint Lithography (NIL) Developments



EVG® HERCULES® NIL SmartNIL® HVM Up to 300 mm



EVG® 770 NT S&R NIL System



EVG® 7300 SmartNIL® and WLO Up to 300 mm

EV Group | Focus on Nanoimprint Lithography (NIL)



Main Driving Markets

Augmented Reality



Biomedical



Optical Sensors



ADAS & Automotive Lighting



ource: ams

Photonic Packaging

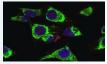


Holographic Displays

Metalenses



Raman Spectro.



 \Rightarrow

NIL is a cost-effective and flexible technology to enable nanostructured surfaces as well microstructures on wafer-level

- Volume-proven wafer level imprinting technology
- Parallel processing of hundreds or thousands of micro- and nanostructures
- High degree of flexibility in optical designs

EVG NIL equipment and dedicated process capabilities → Leading NIL equipment supplier with worldwide largest install base

- Step-and-Repeat Mastering
- SmartNIL®
- Lens Molding
- → Tools from R&D to fully automated HVM

NIL Photonics Competence Center → Innovation Incubator

- Helping to ramp up
- 1.300 m³ class 10 100 cleanroom space & application labs







EV Group | Dominant Share in NIL Photonics Key Markets



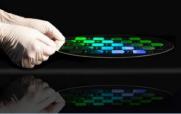
Application

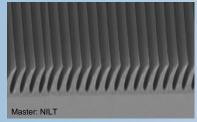
Wafer



Displays & Augmented Reality



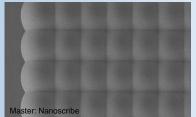




Sensors & Wafer Level Optics



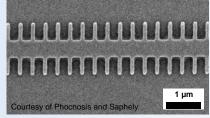




Biomedical Applications









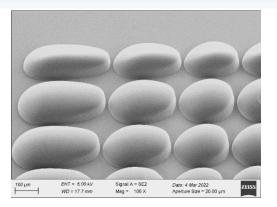
Challenge: HVM manufacturability combined with design and material flexibility

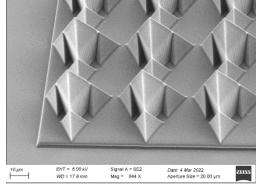
Freeform Microstructures | Results

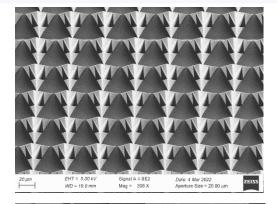


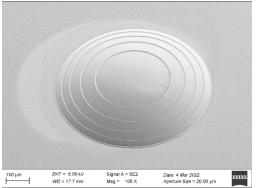


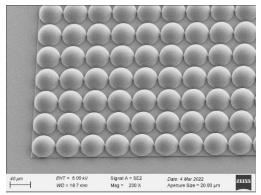
Challenge addressed: Highly flexible freeform microstructures made by NIL with dedicated materials

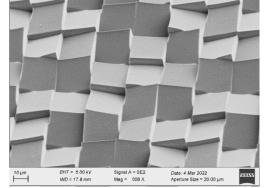














Highly flexible freeform microstructures made by NIL How it works





Template

200/300 mm Master

Multiple Imprints





Single-die freeform master made by 2GL

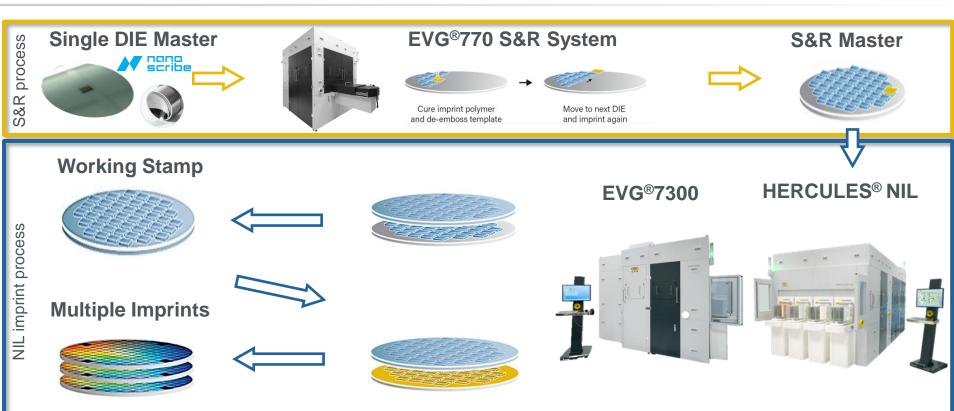


Fully populated S&R Master by made EVG770

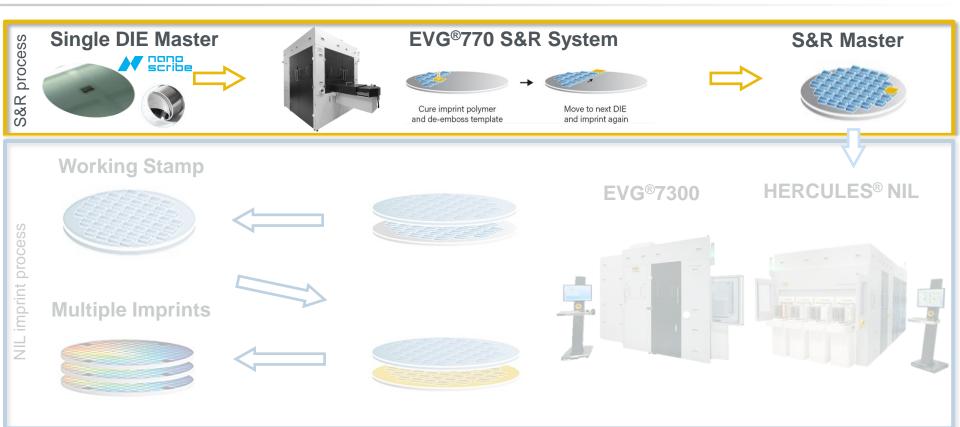


Multiple imprints from working stamps made by EVG7300









Freeform Microstructures | Saving Costs by Scaling

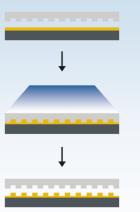


Template 200/300 mm Master Multiple Imprints

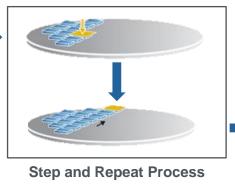


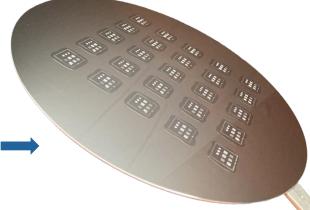
From single die to fully populated 200 mm or 300 mm master by step and repeat







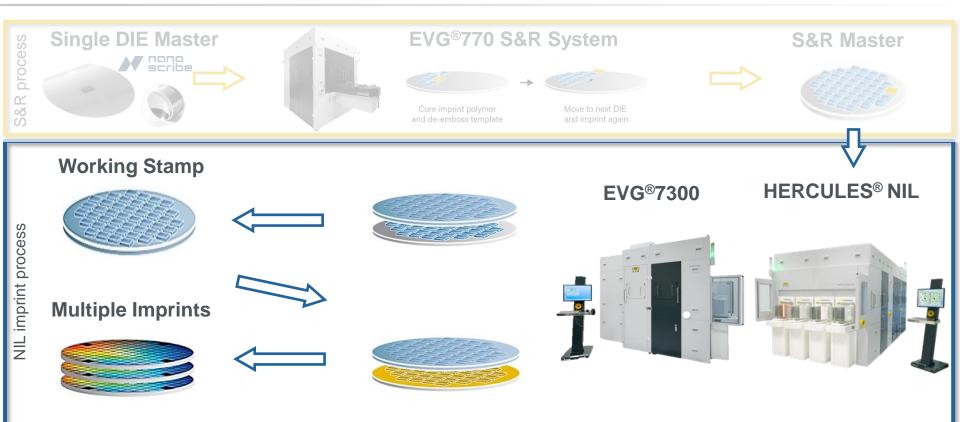




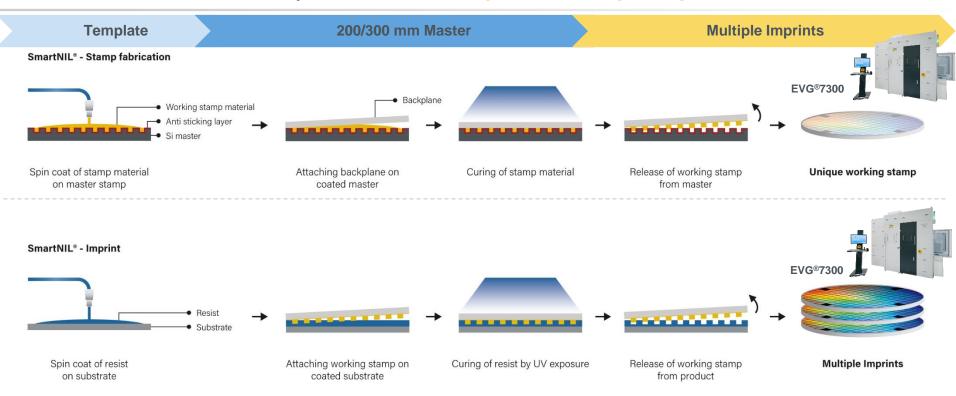
Single-die freeform master made by 2GL

EVG®770 S&R System Fully populated S&R Master











Working stamp manufacturing and imprinting is performed in the same equipment





Template

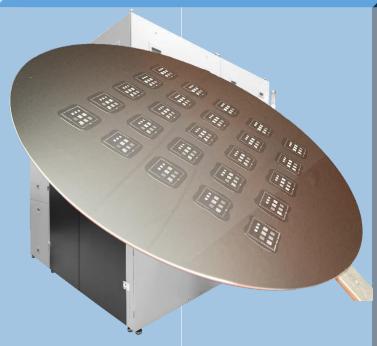
200/300 mm Master

Multiple Imprints

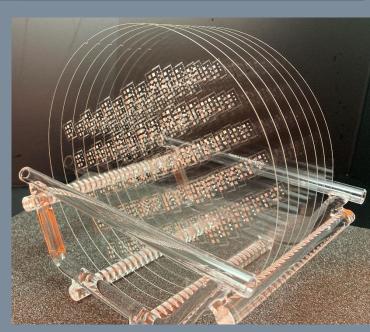




Single-die freeform master made by 2GL



Fully populated S&R Master by made EVG770



Multiple imprints from working stamps made by EVG7300



Monolithic Molding of Freeform Glass Microstructures Results



Freeform Glass Microstructures | Used Material



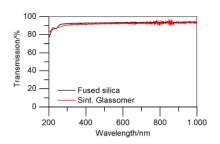
Glassomer "pre-glass" materials → processing glass like polymers

- Glassomer photocurable materials can be structured via NIL, 3D printing, injection molding, ...
- After this polymer processing Glassomer is turned into optical grade fused silica glass during a final heat treatment
- Result: same optical transparency as commercial fused silica and a smooth surface with a roughness of a few nm
- Refractive Index: 1.4589 ± 0.0002
- Abbe Number: 67.1 ± 1.1

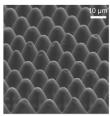
Thermal Resistance



UV/VIS Transparency



∫lassomer





Microstructures for Solar Cells

Microfluidics



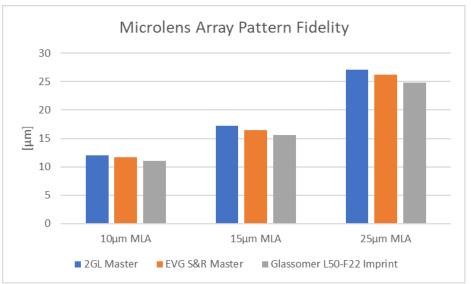
High durability, high transparency, low thermal expansion, long-term clarity without yellowing or scratches → Perfectly fitted for harsh requirements



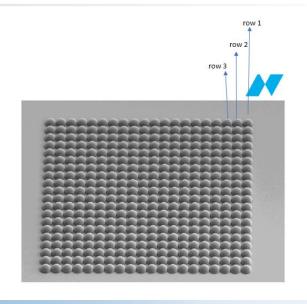


Freeform Glass Microstructures | Results: Pattern Fidelity





0			
10μm MLA	15μm MLA 25μm MLA		
■ 2GL Master ■ EVG S&R Master ■ Glassomer L50-F22 Imprint			
Brassa Chain Height Value			
Process Chain	White Light Interferometry		
Height of 2GL master	12.07	17.21	27.04
Height of S&R master	11.69	16.48	26.18
Height of Glassomer Imprint (not sintered)	11.01	15.65	24.84





Whole process chain height value

- ~ 8.5 % height loss from 2GL master to imprinted glass material
- → Due to material shrinkage
- → Factor is considered when creating the master design
- → Highly reproducible NIL replications

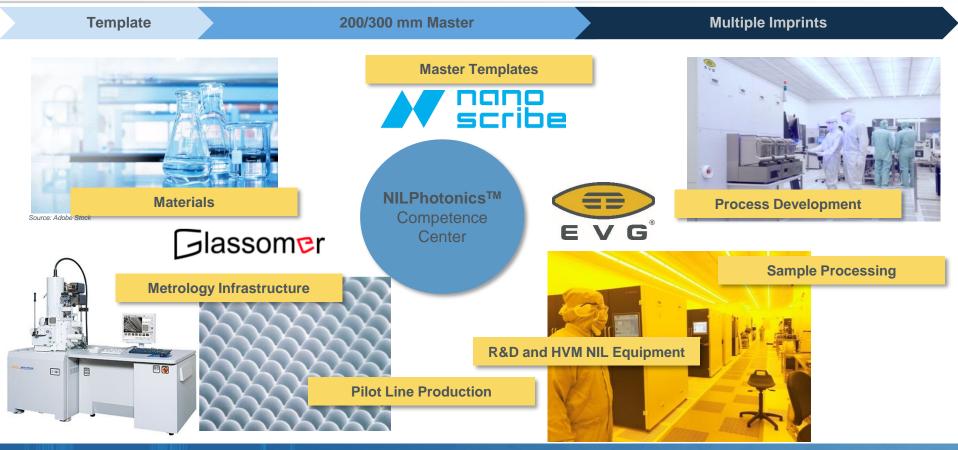




Monolithic Molding of Freeform Glass Microstructures Using NILPhotonics® Competence Center









Monolithic Molding of Freeform Glass Microstructures Summary & EPIC Questions



NIL at EVG | Summary and EPIC Questions





Nanoimprint equipment based manufacturing technologies enable next-generation freeform micro- and nanostructures

- Waver-level based manufacturing → large scaling factor
- Full know-how from single master die to the whole module → processing wafers up to 300 mm
- SmartNIL® Technology → highly flexible and insensitive to shapes and size
- Open materials platform
- NILPhotonics® Competence Center: Innovation Incubator → helping to ramp up





What can we do for you?

→ World Class Facility for...



- NIL Process development
- Joint R&D with partners
- Small volume pilot line production
- S&R mastering service
- NIL Process training

What we are searching for?

→ Collaboration Partners for..



- Mastering
- Design
- New customer challenges ☺





Thank you!

Andrea Kneidinger, Business Development Manager



May 2022

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